

# RGCL60TK60D

### 600V 30A Field Stop Trench IGBT

V <sub>CES</sub>	600V
I <sub>C(100°C)</sub>	18A
V <sub>CE(sat) (Typ.)</sub>	1.4V@I <sub>C</sub> =30A
$P_D$	54W

#### Features

- 1) Low Collector Emitter Saturation Voltage
- 2) Soft Switching
- Built in Very Fast & Soft Recovery FRD (RFN Series)
- 4) Pb free Lead Plating; RoHS Compliant

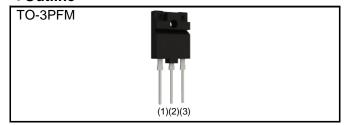
#### Applications

Partial Switching PFC

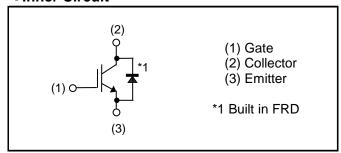
Discharge Circuit

Brake for Inverter

#### Outline



#### ●Inner Circuit



Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Type	Tape Width (mm)	-
Type	Type Basic Ordering Unit (pcs)	450
	Packing Code	C11
	Marking	RGCL60TK60D

### ● Absolute Maximum Ratings (at T<sub>C</sub> = 25°C unless otherwise specified)

Parameter		Value	Unit
Collector - Emitter Voltage		600	V
	$V_{GES}$	±30	V
T <sub>C</sub> = 25°C	I <sub>C</sub>	30	А
T <sub>C</sub> = 100°C	I <sub>C</sub>	18	А
Pulsed Collector Current			А
$T_C = 25^{\circ}C$	I <sub>F</sub>	26	А
T <sub>C</sub> = 100°C	I <sub>F</sub>	15	А
Diode Pulsed Forward Current		100	А
T <sub>C</sub> = 25°C	P <sub>D</sub>	54	W
T <sub>C</sub> = 100°C	P <sub>D</sub>	27	W
Operating Junction Temperature		-40 to +175	°C
Storage Temperature		-55 to +175	°C
	$T_{C} = 100^{\circ}C$ $T_{C} = 25^{\circ}C$ $T_{C} = 100^{\circ}C$ $T_{C} = 25^{\circ}C$	$T_{C} = 25^{\circ}C \qquad I_{C}$ $T_{C} = 100^{\circ}C \qquad I_{C}$ $I_{CP}^{*1}$ $T_{C} = 25^{\circ}C \qquad I_{F}$ $T_{C} = 100^{\circ}C \qquad I_{F}$ $I_{FP}^{*1}$ $T_{C} = 25^{\circ}C \qquad P_{D}$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

<sup>\*1</sup> Pulse width limited by T<sub>jmax.</sub>

#### ●Thermal Resistance

Parameter	Symbol	Values			Unit
raiametei		Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	2.77	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	3.93	°C/W

## ●IGBT Electrical Characteristics (at T<sub>j</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
raiametei		Conditions	Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV <sub>CES</sub>	$I_C = 10 \mu A, V_{GE} = 0 V$	600	1	-	V
Collector Cut - off Current	I <sub>CES</sub>	$V_{CE} = 600V, V_{GE} = 0V$	ı	ı	10	μΑ
Gate - Emitter Leakage Current	I <sub>GES</sub>	$V_{GE} = \pm 30V, \ V_{CE} = 0V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 5V, I_{C} = 18.9 \text{mA}$	4.5	5.5	6.5	V
Collector - Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_C = 30A$ , $V_{GE} = 15V$ $T_j = 25$ °C $T_j = 175$ °C	-	1.4 1.6	1.8 -	V

## ●IGBT Electrical Characteristics (at T<sub>j</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Linit
			Min.	Тур.	Max.	Unit
Input Capacitance	C <sub>ies</sub>	V <sub>CE</sub> = 30V	-	1600	-	
Output Capacitance	C <sub>oes</sub>	$V_{GE} = 0V$	-	38	-	pF
Reverse Transfer Capacitance	C <sub>res</sub>	f = 1MHz	-	29	-	
Total Gate Charge	$Q_g$	V <sub>CE</sub> = 300V	-	68	-	
Gate - Emitter Charge	Q <sub>ge</sub>	I <sub>C</sub> = 30A	-	13	-	nC
Gate - Collector Charge	$Q_{gc}$	V <sub>GE</sub> = 15V	-	27	-	
Turn - on Delay Time	t <sub>d(on)</sub>	$I_C = 30A, V_{CC} = 400V$	-	44	-	
Rise Time	t <sub>r</sub>	$V_{GE} = 15V, R_G = 10\Omega$	-	27	-	no
Turn - off Delay Time	t <sub>d(off)</sub>	T <sub>j</sub> = 25°C	-	186	-	ns
Fall Time	t <sub>f</sub>	Inductive Load	-	178	-	
Turn - on Switching Loss	E <sub>on</sub>	*E <sub>on</sub> includes diode	-	0.77	-	
Turn - off Switching Loss	E <sub>off</sub>	reverse recovery	-	1.11	-	mJ
Turn - on Delay Time	t <sub>d(on)</sub>	$I_C = 30A, V_{CC} = 400V$	-	40	-	
Rise Time	t <sub>r</sub>	$V_{GE} = 15V, R_{G} = 10\Omega$	-	45	-	no
Turn - off Delay Time	t <sub>d(off)</sub>	T <sub>j</sub> = 175°C	-	207	-	ns
Fall Time	t <sub>f</sub>	Inductive Load	-	272	-	
Turn - on Switching Loss	E <sub>on</sub>	*E <sub>on</sub> includes diode	-	0.97	-	m l
Turn - off Switching Loss	E <sub>off</sub>	reverse recovery	-	1.54	-	- mJ
		I <sub>C</sub> = 120A, V <sub>CC</sub> = 480V				
Reverse Bias Safe Operating Area	RBSOA	$V_P = 600V, V_{GE} = 15V$	FU	LL SQUA	RE	-
		$R_G = 60\Omega, T_j = 175^{\circ}C$				

## ullet FRD Electrical Characteristics (at $T_j = 25^{\circ}$ C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Unit
Diode Forward Voltage	$V_{F}$	$I_F = 20A$ $T_j = 25$ °C $T_j = 175$ °C	-	1.45 1.25	1.9 -	V
Diode Reverse Recovery Time	t <sub>rr</sub>		-	58	-	ns
Diode Peak Reverse Recovery Current	I <sub>rr</sub>	I <sub>F</sub> = 20A V <sub>CC</sub> = 400V	-	6.3	-	А
Diode Reverse Recovery Charge	$Q_{rr}$	di <sub>F</sub> /dt = 200A/µs T <sub>j</sub> = 25°C	-	0.20	-	μC
Diode Reverse Recovery Energy	E <sub>rr</sub>		-	7.4	-	μJ
Diode Reverse Recovery Time	t <sub>rr</sub>	$I_F = 20A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	256	-	ns
Diode Peak Reverse Recovery Current	I <sub>rr</sub>		-	10.4	1	А
Diode Reverse Recovery Charge	$Q_{rr}$		-	1.35	-	μC
Diode Reverse Recovery Energy	E <sub>rr</sub>		-	146.5	-	μJ

Fig.1 Power Dissipation vs. Case Temperature

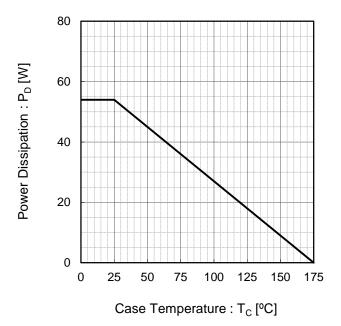


Fig.2 Collector Current vs. Case Temperature

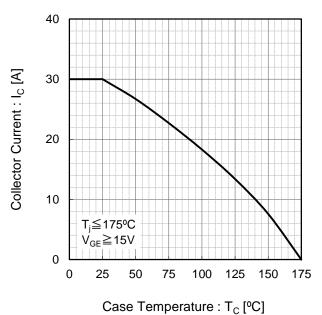


Fig.3 Forward Bias Safe Operating Area

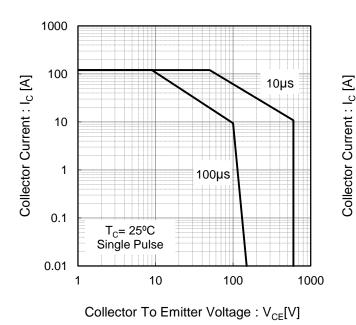


Fig.4 Reverse Bias Safe Operating Area

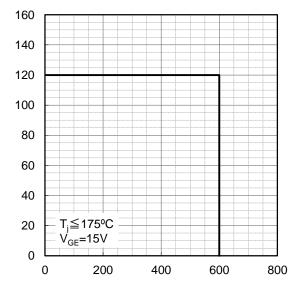


Fig.5 Typical Output Characteristics

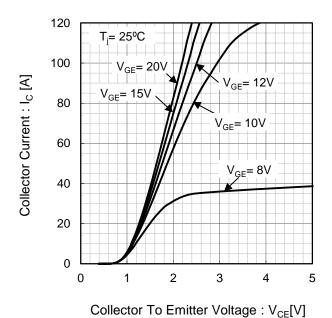
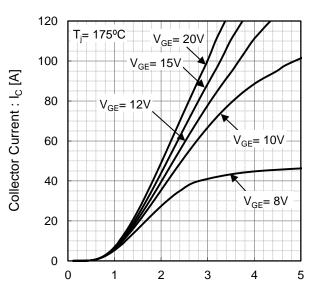


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage : V<sub>CE</sub>[V]

Fig.7 Typical Transfer Characteristics

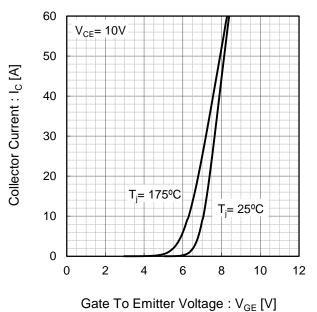
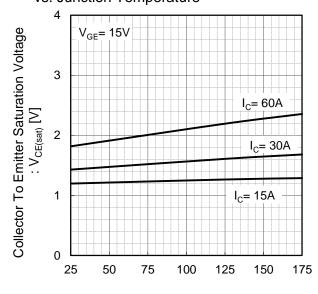


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature



Junction Temperature : T<sub>i</sub> [°C]

Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

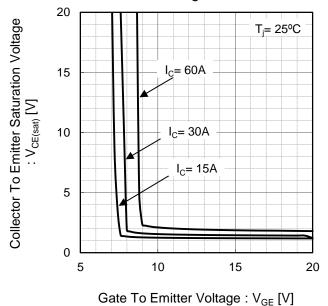
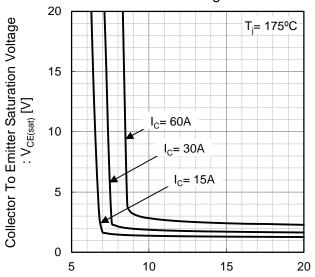


Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage: V<sub>GE</sub> [V]

Fig.11 Typical Switching Time

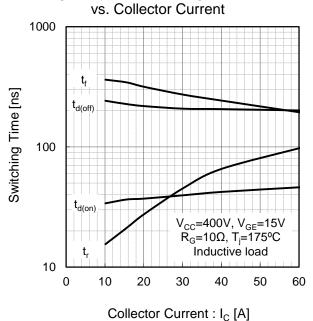
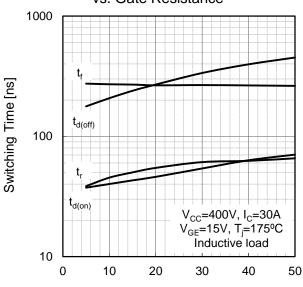


Fig.12 Typical Switching Time vs. Gate Resistance



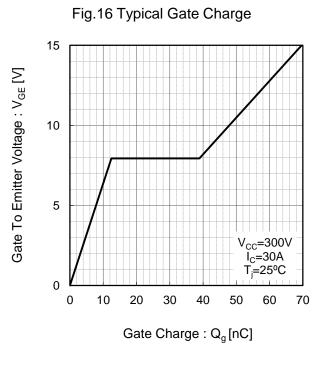
Gate Resistance :  $R_G[\Omega]$ 

Fig.13 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1  $\mathsf{E}_{\mathsf{off}}$ 0.1  $V_{CC}$ =400V,  $V_{GE}$ =15V  $R_{G}$ =10 $\Omega$ ,  $T_{j}$ =175°C Inductive load 0.01 0 10 20 40 50 30 60 Collector Current : I<sub>C</sub> [A]

vs. Gate Resistance 10 Switching Energy Losses [mJ]  $\mathsf{E}_{\mathsf{off}}$ 1 Eon 0.1  $V_{CC}$ =400V,  $I_{C}$ =30A  $V_{GE}$ =15V,  $T_{j}$ =175°C Inductive load 0.01 0 10 20 30 40 50 Gate Resistance :  $R_G[\Omega]$ 

Fig.14 Typical Switching Energy Losses

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 Cies 1000 Capacitance [pF] 100 Coes Cres 10 f=1MHz  $V_{GE}=0V$ T;=25°C 0.01 0.1 1 10 100 Collector To Emitter Voltage : V<sub>CE</sub>[V]



0

0.5

#### **•**Electrical Characteristic Curves

Vs. Forward Voltage

80

[V] 60

40

T<sub>j</sub>= 175°C

T<sub>j</sub>= 25°C

1.5

Forward Voltage: V<sub>F</sub>[V]

2

2.5

3

Fig.17 Typical Diode Forward Current

Fig.18 Typical Diode Reverse Recovery Time vs. Forward Current 400  $V_{CC}$ =400V di<sub>F</sub>/dt=200A/µs Reverse Recovery Time: t<sub>rr</sub> [ns] Inductive load 300 T<sub>i</sub>= 175°C 200 100 T<sub>i</sub>= 25°C 0 10 20 30 40 50

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

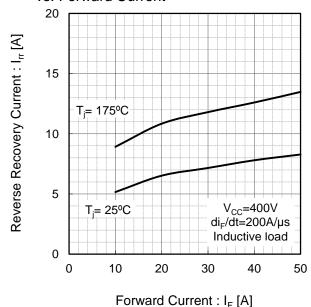
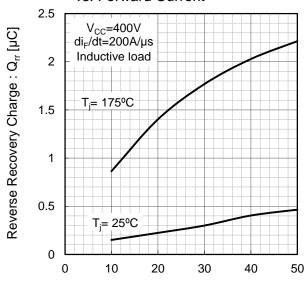


Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current

Forward Current : I<sub>F</sub> [A]



Forward Current : I<sub>F</sub> [A]

Fig.21 IGBT Transient Thermal Impedance

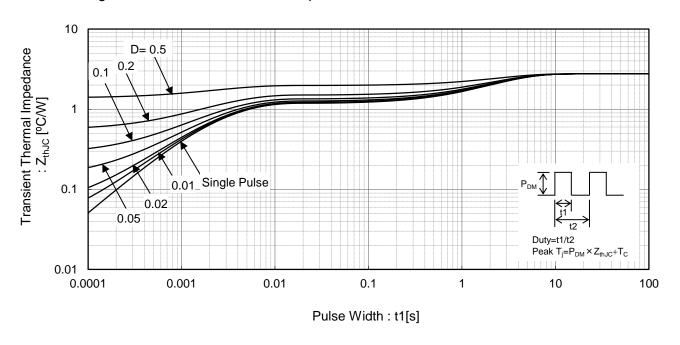
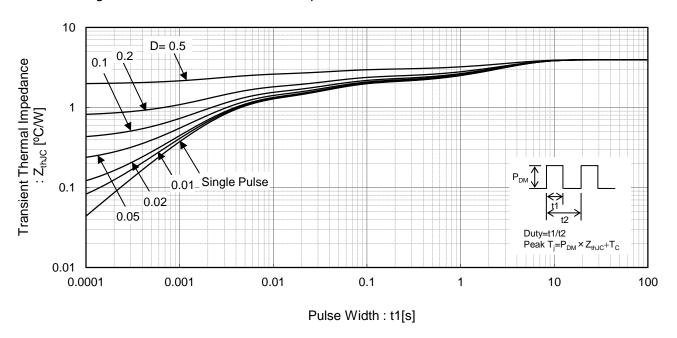


Fig.22 Diode Transient Thermal Impedance



### ●Inductive Load Switching Circuit and Waveform

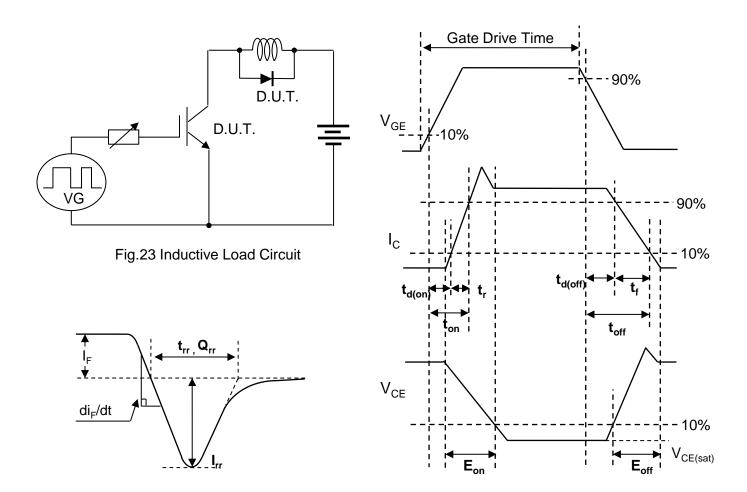


Fig.25 Diode Reverce Recovery Waveform

Fig.24 Inductive Load Waveform

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